

## ABSTRACT

The present invention provides a surface-mount SAW device configured to prevent sealing resin layer coated all over the top 5 surface of a piezoelectric substrate from becoming charged even if the piezoelectric substrate forming the SAW device is made of a pyroelectric material. The SAW device is composed of: a mounting substrate 2; a SAW chip 15 provided with a piezoelectric substrate 18, an IDT electrode 17 formed on one surface of said piezoelectric 10 substrate, and connection pads 16 connected via conductor bumps 10 to conductor traces 5; and a sealing resin layer 21 coated all over the outer surface of the SAW chip flip-chip mounted on the mounting substrate and extended down to the top surface of the mounting substrate to define an airtight space S between the IDT 15 electrode and the mounting substrate; wherein the crystal structure of the piezoelectric substrate belongs to any one of point groups  $C_1$ ,  $C_2$ ,  $C_s$ ,  $C_{2v}$ ,  $C_4$ ,  $C_{4v}$ ,  $C_3$ ,  $C_{3v}$ ,  $C_6$  and  $C_{6v}$  in terms of Schoenflies symbols; characterized in that the conductivity of the piezoelectric substrate is increased to suppress charging of the 20 sealing resin layer.